

IN THE CLAIMS:

1. (Currently Amended) An LED mounting module for having LED devices which are to be mounted thereon, the LED mounting module comprising:

a substrate including at least one insulation board made of an insulation material, and a wiring pattern on which the LED device is to be mounted and which is disposed to cover at

5 least part of a main surface of the insulation board; and

a reflecting member made of a resin material and having a reflecting hole in a position corresponding to each LED devices which is to be mounted on one of main surfaces of the substrate, wherein

the resin material composing the reflecting member is identical in type with a
10 resin material composing the insulation board.

the reflecting member has a lower surface part of which is directly adhered to part of the wiring pattern opposing the part of the lower surface with use of the resin material composing the reflecting member,

and a remainder of which is directly adhered to part of the insulation board
15 opposing the remainder of the lower surface with use of the resin material composing the reflecting member.

2. (Currently Amended) The LED mounting module of Claim 1, wherein

the reflecting member and the insulation board are both made of the resin material containing one or more fillers, and are clouded by the fillers.

~~a resin material forming the insulation board contains a same resin as the resin~~
5 ~~material forming the reflecting member.~~

3. (Original) The LED mounting module of Claim 1, wherein
the resin material is a thermosetting resin material principally containing an epoxy
resin .

4. (Previously Presented) The LED mounting module of Claim 1, wherein
the wiring pattern is a surface pattern on which each LED device is to be
mounted, and

the surface pattern excluding an area corresponding to the reflecting hole is
5 entirely covered with the reflecting member.

5. (Previously Presented) The LED mounting module of Claim 4, wherein
the wiring pattern has another pattern being not formed on the main surface of the
insulation board, and

a via hole electrically connecting the other pattern and the surface pattern is
5 formed within the insulation board in an area corresponding to the lower surface of the reflecting
member.

6.-27. (Cancelled)

28. (New) An LED mounting module for having a plurality of LED devices which are to be mounted thereon, the LED mounting module comprising:

a substrate including at least one insulation board made of an insulation material, and a wiring pattern disposed to cover at least part of a main surface of the insulation board;

5 a metal board layered on another surface of the substrate;

a plurality of reflecting members provided on one of main surfaces of the substrate and each provided at a position corresponding to one of the plurality of LED devices which is to be mounted, and each having a reflecting hole in the position, wherein

the reflecting members are each made of a resin material having one or more
10 fillers that enhances reflectance efficiency,

the resin material composing the reflecting member is identical in type with a resin material composing the insulation board,

the reflecting member and the insulation board are clouded by the fillers,

the reflecting member has a lower surface part of which is directly adhered to part
15 of the wiring pattern opposing the part of the lower surface with use of the resin material composing the reflecting member, and

a remainder of which is directly adhered to part of the insulation board opposing the remainder of the lower surface with use of the resin material composing the reflecting member.